

Electronic Patent Application Fee Transmittal

Application Number:	10620346			
Filing Date:	17-Jul-2003			
Title of Invention:	Copper paste, wiring board using the same, and production method of wiring board			
First Named Inventor/Applicant Name:	Hiroshi Sumi			
Filer:	Abraham Jacob Rosner/Kelley Liphard			
Attorney Docket Number:	Q76616			

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 2 months with \$0 paid	1252	1	460	460
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				1270